

STAUF

— seit 1828 —



STAUF RM

High-quality cement-based levelling compounds for thick layer compensation work under parquet or elastic/textile floor coverings



Technical Datasheet

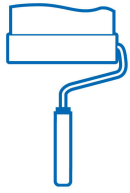
Product number	✓ 133110
Special features	<ul style="list-style-type: none">✓ stable✓ fine grain✓ fast drying✓ low in pores
Application range	<ul style="list-style-type: none">✓ levelling of height differences✓ high-quality, cement-based levelling compound for thick layer compensation work✓ Filling and levelling of holes and hollows on screed, steps and platforms
Suitable subfloors	<ul style="list-style-type: none">✓ sanded mastic asphalt screed✓ concrete C 25 / 30 according to DIN 1045 (non-skid surface)✓ calcium sulphate (flow) floors✓ Raised access floors✓ wooden planks, wood fibre boards✓ STAUF levelling compounds✓ magnesite and plaster floors✓ chipboards (P4 to P7), OSB boards (OSB/2 to OSB/4)✓ unlaminated gypsum fibre boards✓ cement floors✓ cavity floors
Suitable primers	<ul style="list-style-type: none">✓ STAUF VDP 130✓ STAUF VPU 155 S + STAUF quartz sand✓ STAUF D 54✓ STAUF VDP 160✓ STAUF VEP 195 + STAUF quartz sand✓ STAUF WEP 180 + STAUF quartz sand
Product properties	<ul style="list-style-type: none">✓ suitable on subfloor heating systems✓ high strength✓ crack-free even in thicker layers✓ tension reducing✓ suitable for castors swivel chairs according to DIN EN 12529
Color	✓ grey

Consumption in g/m ² per mm layer thickness	✓ 1600g per mm layer thickness
Accessibility/ready for foot traffic	✓ after 30 minutes at 20 °C, max 65% rel. humidity
Ready for installation	✓ after 4 hours ≤ 3 CM%
Additional instructions 1	✓ Without flammable components in accordance with DIN 4102: A1 and DIN EN 13501: A1fl.
Room climate at work site	✓ Minimum 18 °C, maximum 75% rel. humidity, preferably max. 65%
Transport requirements	✓ dry
Storage requirements	✓ dry ✓ cool
Shelf-life	✓ 9 months
Giscode	✓ ZP1
Emicode	✓ EC1 plus
Available packaging	✓ 25 kg paper bag
layer thickness	✓ 1 - 10 mm without aggregates ✓ 10 - 50 mm with aggregates
Processing time	✓ approx. 15 minutes at 20 °C and 65% rel. humidity
Mixing ratio component A	✓ layer thickness 1 - 10 mm: 25 kg levelling compound ✓ layer thickness 10 - 20 mm: 25 kg levelling compound and 12 kg quartz sand ✓ layer thickness 20 - 50 mm: 25 kg levelling compound and 25 kg quartz sand
Mixing ratio component B	✓ 5.5 liter water



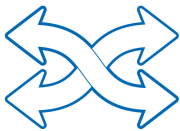
EXAMINATION OF SUBFLOOR

Prior to processing, the subfloor must be checked according to the standard DIN 18356, DIN 18365 or corresponding national standards. The subfloor shall be resistant to pressure and tension, free of cracks, must have sufficient surface strength, be permanently dry, level, clean and free of from contaminants that may prevent adhesion, sinter layers etc. In addition, porosity and grip of surface need to be checked. Also check moisture content and absorption of subfloors as well as temperature, air humidity and subfloor temperature.



SUBFLOOR PREPARATION

It must be ensured that the subfloor is ready for installation by performing proper subfloor preparation, floors must be clean, have sufficient surface strength, must be level, permanently dry and free of cracks. A mechanical pretreatment of the subfloor (sweeping, vacuuming, mechanical brushing, sanding, milling, shot blasting) must be performed depending on type and condition of subfloor. Cracks and joints, except expansion joints and other construction joints, shall be solidly closed with STAUF repair resin and floor brackets. Cavities and indentations can be filled with a non self-levelling STAUF levelling compound. In order to improve adhesion of adhesives and leveling compounds, prime the subfloor with the appropriate primer.



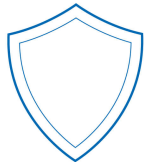
MIXING PROCEDURE OF COMPONENTS

Add specified amount of water (clean and cold) into clean mixing bucket. Add complete content of container and stir evenly. For mixing, use an electrical stirrer with approx. 600 - 800 rpm with spiral or large paddle mixer. Mix until you have a homogeneous compound. Mix for another two minutes, wait one minute and then stir again for one minute (does NOT apply for non-self levelling compounds). Pour the required amount of (clean and cold) water, according to the specified mixing ratio, into a clean mixing vessel. Do not mix more material than you can apply within 15 minutes. Extending the levelling compound: To achieve higher layer thickness, the levelling compound can be extended with STAUF quartz sand.



PROCESSING

Mix levelling compound with cold, clean water. If required, fillers is added as last component. Then, spread, smooth or model the levelling compound using a smoothing trowel or notched trowel. Process the compound during pot life. Lower temperatures or higher ambient humidity delay the period until floor is ready for installation. The compound sets hydraulically, which means that it needs to be protected from direct sunlight and draughts. Before applying a further layer of filler or levelling compound, apply an intermediate layer of STAUF dispersion primer for filler compounds. Do not prime levelling and filler compounds before direct adhesion. The maximum specified layer thickness must not be exceeded when applying two coats of trowel. The thickness of the second coat must not be higher than that of the first coat. Best for use at 18 - 25 °C, substrate temperature between 15 - 23 °C (with underfloor heating 18 - 22 °C) and relative humidity below 65 %, until the adhesive has set.



LIMITATION OF LIABILITY

The foregoing representations are based on the results of our most current product and material testing and are of a non-obligatory advisory nature only since we have no control over the actual quality of workmanship, materials used and worksite conditions. As such, they do not constitute an express or implied warranty of any kind. The same applies to our commercial and technical consultation services which are provided free-of-charge and without obligation. Therefore, we strongly recommend that prior on-site testing be conducted to observe and study the suitability of the product for the intended purpose. With the release of this technical information, all prior technical information (technical data sheets, installation recommendations and other information regarding similar purposes) becomes invalid.